



SOT685-1

plastic thermal enhanced very thin small outline package; no leads; 8 terminals; body 6 x 5 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HVSON8; QFPK
Package type industry code	HVSON8; QFPK
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	27-11-2002

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		4.85	-	5	5.15	mm
E	package width		5.85	-	6	6.15	mm
A	seated height		[tbd]	-	0.85	1	mm
A ₂	package height		[tbd]	-	0.85	[tbd]	mm
n ₂	actual quantity of termination		-	-	8	-	



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2. Package outline

**HVSON8: plastic thermal enhanced very thin small outline package; no leads;
8 terminals; body 6 x 5 x 0.85 mm**

SOT685-1

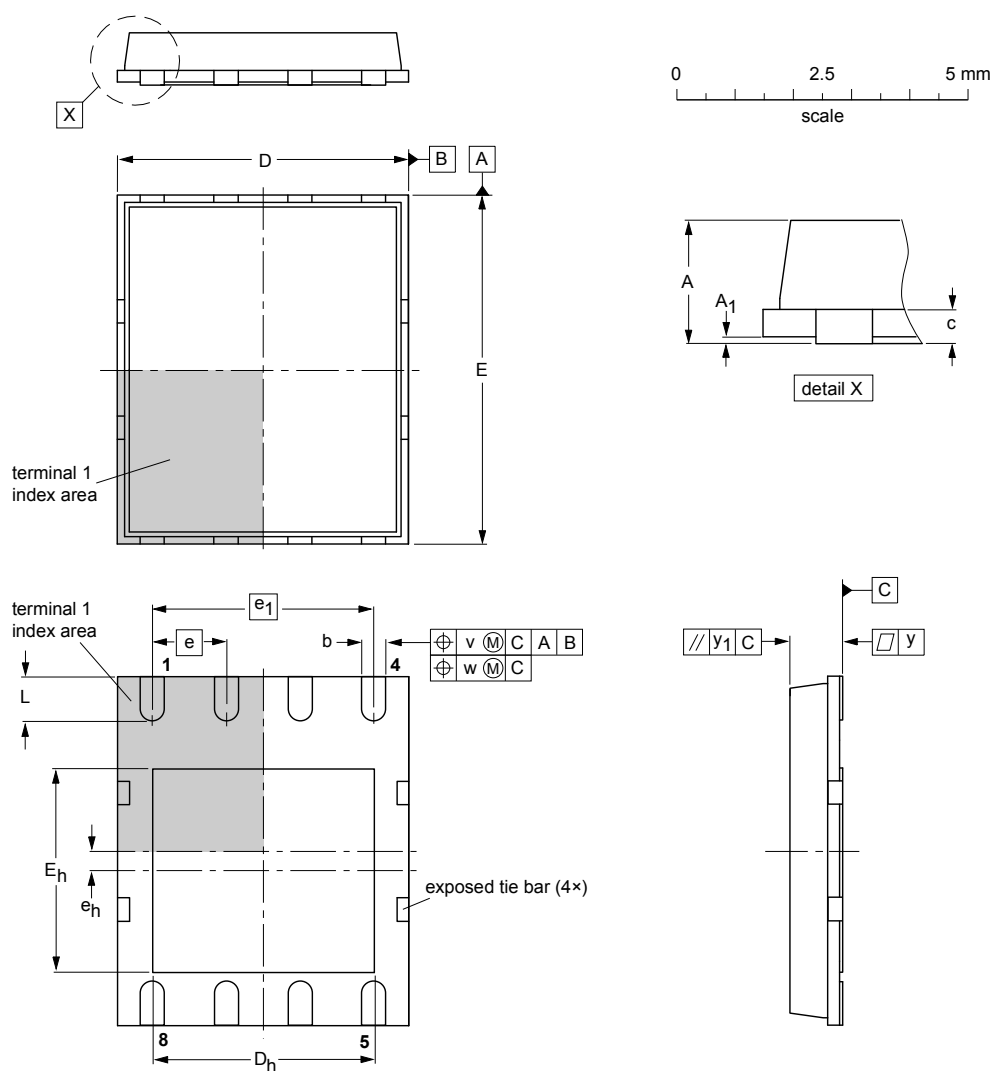


Fig. 1. Package outline HVSON8; QFPK (SOT685-1)

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3. Soldering

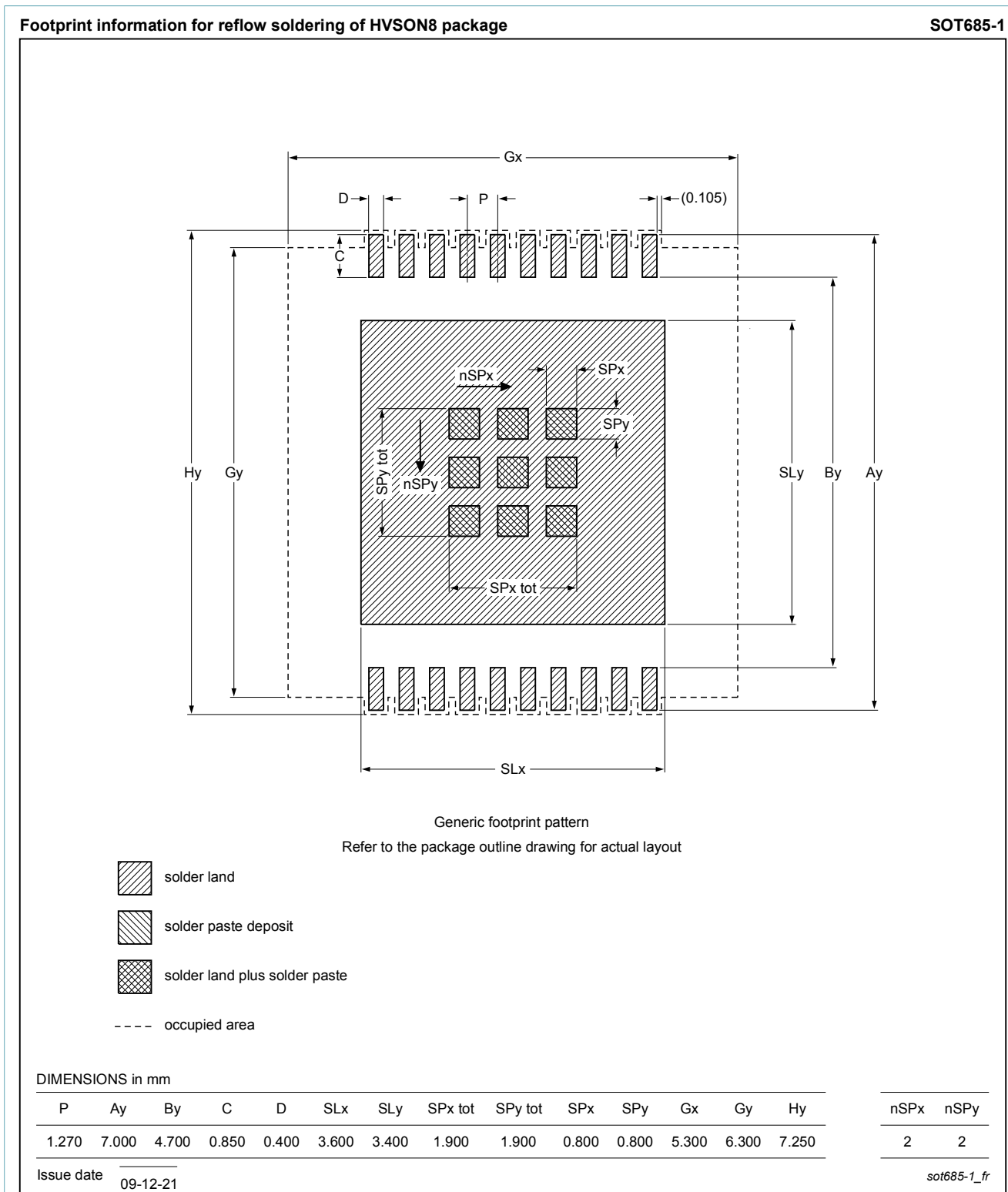


Fig. 2. Reflow soldering footprint for HVSON8; QPAK (SOT685-1)

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4. Legal information

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